



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Paul et al.

Application No. 10/803,502

Filed: March 17, 2004

Confirmation No. 5691

For: METHOD FOR MAKING DEVICES
HAVING INTERMETALLIC
STRUCTURES AND INTERMETALLIC
DEVICES MADE THEREBY

Examiner: Unknown

Art Unit: 3729

Attorney Reference No. 245-68071-01

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Attorney or Agent
for Applicant(s)

Date Mailed October 5, 2005

TRANSMITTAL LETTER

Enclosed for filing in the application referenced above are the following:

- ☒ Information Disclosure Statement
- ☒ Form 1449 and references cited thereon
- ☒ The Director is hereby authorized to charge any additional fees that may be required, or credit over-payment, to Deposit Account No. 02-4550. A copy of this sheet is enclosed.
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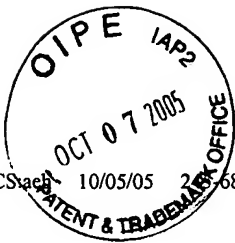
Respectfully submitted,

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Registration No. 36,011

cc: Docketing



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PATENT

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Date Mailed October 6, 2005

**INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. § 1.97(b)(3)**

COMMISSIONER FOR PATENTS
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Listed on the accompanying form PTO-1449 and enclosed herewith are several English-language documents. Applicants respectfully request that these documents be listed as references cited on the issued patent.

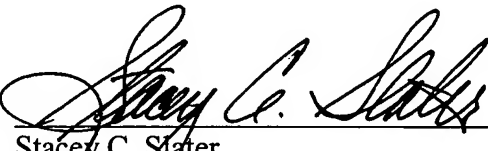
Copies of United States patents and United States published patent applications do not have to be provided to the Patent Office (37 C.F.R. 1.98(a)(2)(ii)). Copies of unpublished U.S. applications do not have to be provided, as long as the application is available on PAIR, as this requirement of 37 C.F.R. § 1.98(a)(2)(iii) has been waived by the United States Patent and Trademark Office pursuant to the Official Gazette Notice on October 19, 2004 (1287 OG 163). Applicants will provide copies of such patents or applications upon request.

Applicants filed this Information Disclosure Statement ("IDS") before the mailing date of a first Office action on the merits. As a result, no fee should be required to file this IDS. However, if the Patent Office determines that a fee is required for Applicants to file this IDS, please charge any such fees, or credit overpayment, to Deposit Account No. 02-4550. A **duplicate** copy of this Information Disclosure Statement is enclosed.

The filing of this IDS shall not be construed to be an admission that the information cited in the statement is, or is considered to be, prior art or otherwise material to patentability as defined in 37 C.F.R. §1.56.

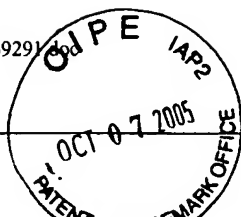
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Examiner Name	Unknown

Examiner's Initials*	Cite No. (optional)	OTHER DOCUMENTS
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		Peterson, "Numerical Modeling of Conduction Effects in Microscale Counterflow Heat Exchangers," <i>Microscale Thermophysical Engineering</i> , 3:17-30, 1999.	
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